T-1 3/4 (5mm) SOLID STATE LAMP

Part Number: WP7113SRD14V



ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

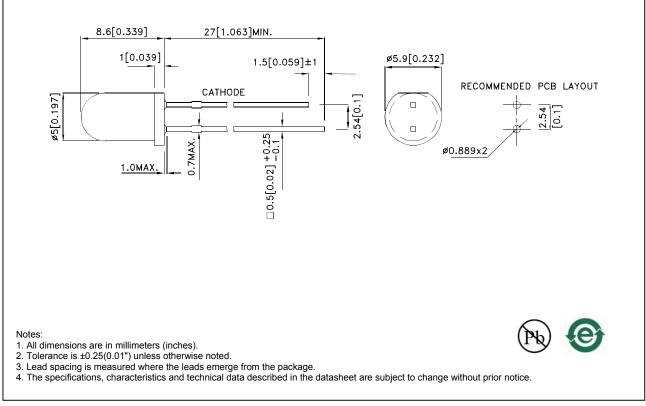
Features

- Low power consumption.
- Popular T-1 3/4 diameter package.
- General purpose leads.
- Reliable and rugged.
- Long life solid state reliability.
- Available on tape and reel.
- 14V internal resistor.
- RoHS compliant.

Descriptions

- The Super Bright Red source color devices are made with Gallium Aluminum Arsenide Red Light Emitting Diode.
- Electrostatic discharge and power surge could damage the LEDs.
- It is recommended to use a wrist band or antielectrostatic glove when handling the LEDs.
- All devices, equipments and machineries must be electrically grounded.

Package Dimensions



DATE: JAN/23/2015 DRAWN: P.Cheng PAGE: 1 OF 6 ERP: 1101005268

Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] V= 14V		Viewing Angle [1]
			Min.	Тур.	201/2
WP7113SRD14V	Suman Dright Dad (Ca AlAa)	Ded Diffused	180	300	- 30°
	Super Bright Red (GaAlAs)	Red Diffused	*60	*100	

Notes:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

Luminous intensity/ luminous Flux: +/-15%.
*Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Red	655		nm	VF=14V
λD [1]	Dominant Wavelength	Super Bright Red	640		nm	VF=14V
Δλ1/2	Spectral Line Half-width	Super Bright Red	20		nm	VF=14V
lf	Forward Current	Super Bright Red	10.5	13.5	mA	VF=14V
IR	Reverse Current	Super Bright Red		10	uA	VR = 5V

Notes:

1. Wavelength: +/-1nm.

2. Wavelength value is traceable to the CIE127-2007 compliant national standards.

3. Excess driving current and/or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

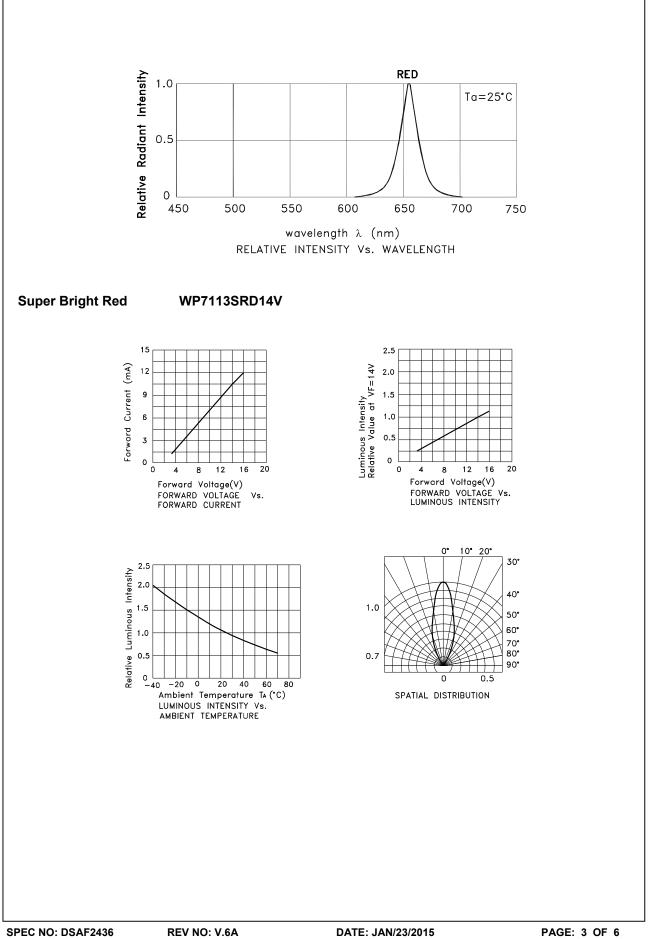
Absolute Maximum Ratings at TA=25°C

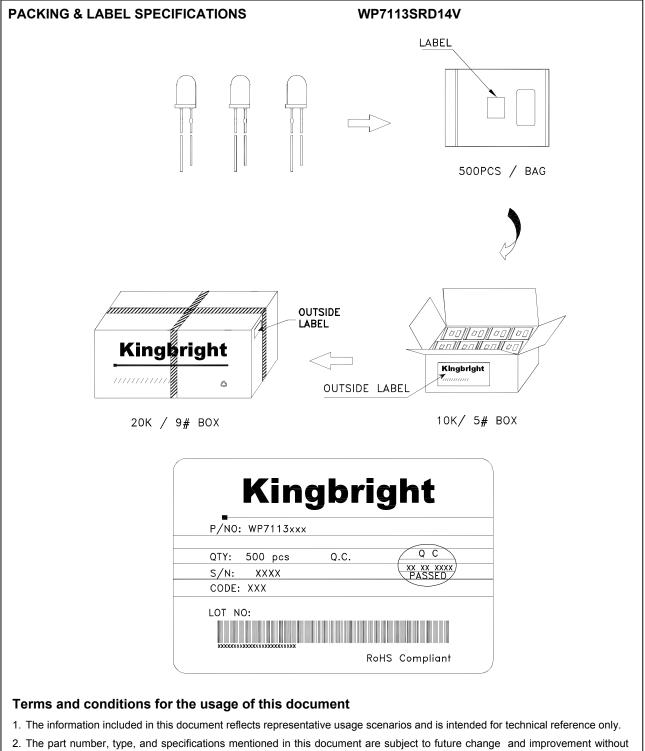
Parameter	Super Bright Red	Units		
Power dissipation	160	mW		
Forward Voltage	16	V		
Reverse Voltage	5	V		
Operating Temperature	-40°C To +70°C			
Storage Temperature	-40°C To +85°C			
Lead Solder Temperature [1]	260°C For 3 Seconds			
Lead Solder Temperature [2]	260°C For 5 Seconds	260°C For 5 Seconds		

Notes:

2. 5mm below package base.
5mm below package base.

DATE: JAN/23/2015 **DRAWN: P.Cheng**



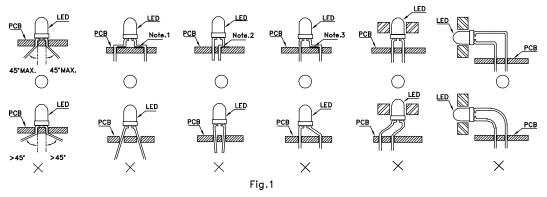


- notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- 3. When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.
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PRECAUTIONS

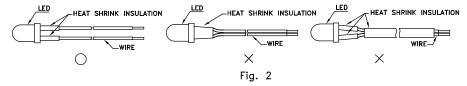
- 1. Storage conditions:
 - a.Avoid continued exposure to the condensing moisture environment and keep the product away from rapid transitions in ambient temperature.
 - b.LEDs should be stored with temperature \leq 30°C and relative humidity < 60%.
 - c.Product in the original sealed package is recommended to be assembled within 72 hours of opening. Product in opened package for more than a week should be baked for 30 (+10/-0) hours at 85 ~ 100°C.
- 2. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)



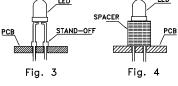
" \bigcirc " Correct mounting method "imes" Incorrect mounting method

Note 1-3: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

3. When soldering wires to the LED, each wire joint should be separately insulated with heat-shrink tube to prevent short-circuit contact. Do not bundle both wires in one heat shrink tube to avoid pinching the LED leads. Pinching stress on the LED leads may damage the internal structures and cause failure. (Fig. 2)



4. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.



- 5. Maintain a minimum of 3mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)
- 6. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)

